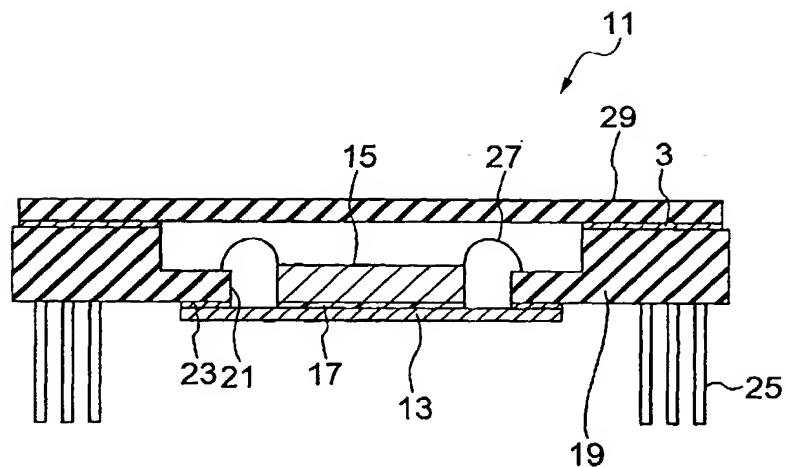


10/009822

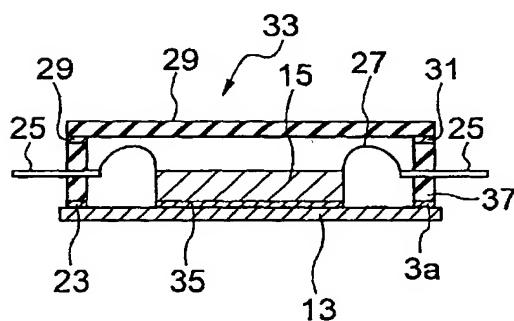
OSADA et al Q67726
MATERIAL FOR A HEAT DISSIPATION
SUBSTRATE FOR MOUNTING A
SEMICONDUCTOR, METHOD OF PRODUCING ..
Filed: December 13, 2001
Alan J. Kasper 202-293-7060
1 of 3

FIG. 1



10009822 10009822

FIG. 2



10/009822

FIG. 3

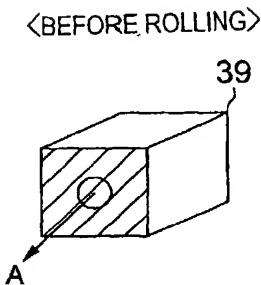


FIG. 4

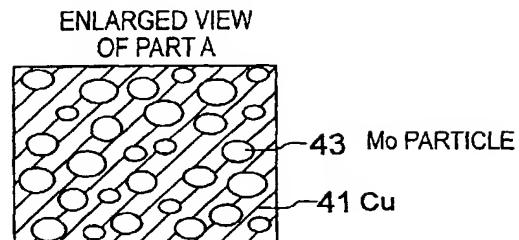


FIG. 5

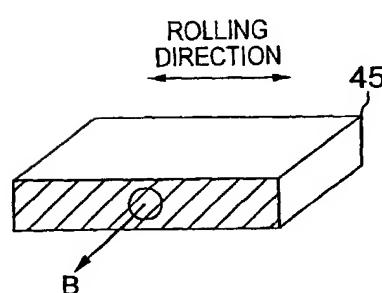
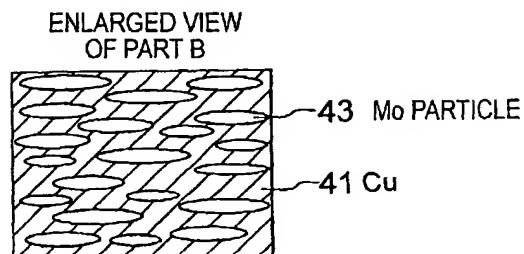


FIG. 6



10/009822

FIG. 7

